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Qualification and Performance Specification for Rigid Printed Boards

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Qualification and Performance Specification for Rigid Printed Boards

Developed by the Rigid Printed Board Performance Specifications Task
Group (D-33a) of the Rigid Printed Board Committee (D-30) of IPC

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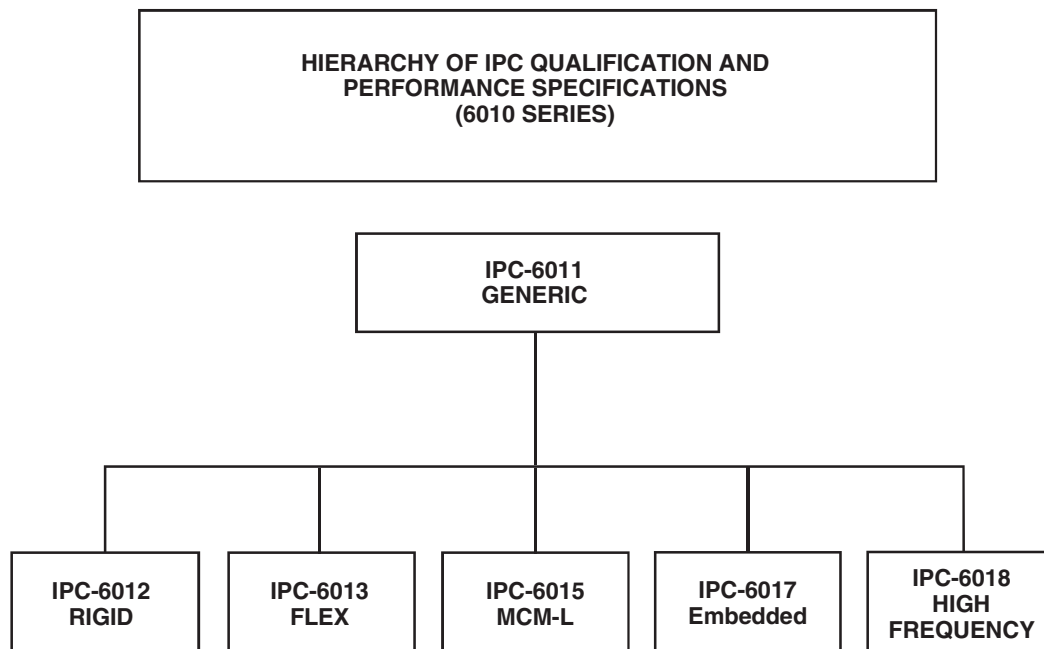
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Contact:

IPC
3000 Lakeside Drive, Suite 105N
Bannockburn, Illinois
60015-1249
Tel 847 615.7100
Fax 847 615.7105

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FOREWORD

This specification is intended to provide information on the detailed performance criteria of rigid printed boards. It supersedes IPC-6012B and was developed as a revision to those documents. The information contained herein is also intended to supplement the generic requirements identified in IPC-6011. When used together, these documents should lead both manufacturer and customer to consistent terms of acceptability.

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As technology changes, a performance specification will be updated, or new focus specifications will be added to the document set. The IPC invites input on the effectiveness of the documentation and encourages user response through completion of "Suggestions for Improvement" forms located at the end of each document.

Acknowledgment

Any document involving a complex technology draws material from a vast number of sources across many continents. While the principal members of the Rigid Printed Board Performance Specifications Task Group (D-33a) of the Rigid Printed Board Committee (D-30) are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the IPC extend their gratitude.

Rigid Printed Board Committee	Rigid Printed Board Performance Specifications Task Group	Technical Liaison of the IPC Board of Directors
Chair Cliff Maddox Boeing Company	Co-Chairs Mark Buechner BAE Systems Randy Reed R. Reed Consultancy LLC	Bob Neves Microtek (Changzhou) Laboratories
Rigid Printed Board Performance Specifications Task Group		
Elizabeth A. Allison, NTS - Baltimore	Jiong (Crystal) Dai, Shennan Circuits Co. Ltd.	Hardeep S. Heer, FTG Circuits
David Anderson, Raytheon Company	Cesar De Luna, NTS - Anaheim	Philip M. Henault, Raytheon
Norman Armendariz, Raytheon Company	Radu C. Dinica, TTM Technologies	Allen Holl, TTM Technologies
Lance A. Auer, Conductor Analysis Technologies, Inc.	Don Dupriest, Lockheed Martin Missiles & Fire Control	Joe Hughes, Hughes Circuits, Inc.
Jimmy Baccam, Lockheed Martin Missiles & Fire Control	Julie Ellis, TTM Technologies	Frank Huijsmans, PIEK International Education Centre (I.E.C.) BV
Chris R. Ballou, TTM Technologies Inc.	Judi Emerson, Flex-N-Gate	Joseph E. Kane, BAE Systems
Tiberiu Baranyi, Flextronics Romania SRL	Gary F. Erickson, Sanmina Corporation	Don Kaufman, Cirexx International, Inc.
John A. Bauer, Collins Aerospace	Richard K. Etchells, Electronic Technology Resource Partners	Allen Keeney, Johns Hopkins University
James Frederick Blanche, NASA Marshall Space Flight Center	Stephan Dennis Evans, L3Harris Communications	Warren S. Kenzie, MacDermid Alpha Automotive
William Bowerman, MacDermid Enthone Electronics Solutions	Robert Farfan, TTM Technologies	Suriyakan Vongtragool, Kleitz Schlumberger Well Services
Scott A. Bowles, Lockheed Martin Corporation	Gary M. Ferrari, FTG Circuits	Kelly Kovalovsky, BAE Systems
Steven A. Bowles, DuPont SVTC	Chris Fitzgerald, Nasa Goddard Space Flight Center	Ernest J. Kreiner, L3Harris
Alex Chandy, Advanced Circuits - Chandler Division	Eric Foote, GE Aviation	Nick S. Koop, TE Connectivity
Denise Charest, Amphenol Printed Circuits, Inc.	William Fox, Lockheed Martin Missile & Fire Control	Kevin Kusiak, Lockheed Martin Corporation
Patrice Chetanneau, Sagem	Bryan Gahan, Electrotek Corp.	Meredith LaBeau, Calumet Electronics Corp.
Thomas Joe Clark, Lockheed Martin Missiles & Fire Control	Mahendra S. Gandhi, Northrop Grumman Aerospace Systems	Jeremy Lakoskey, Honeywell International
Carl Colangelo, Dow Electronic Materials	Gonzalo J Garcia Leypon, Cirexx International, Inc.	Leo P. Lambert, EPTAC Corporation
Michael A. Collier, Teledyne Leeman Labs	Pierre-Emmanuel Goutorbe, Airbus Defence & Space	Christina Landon, NSW Crane
Robert W. Cooke NASA, Marshall Space Flight Center	Ty Gragg, Unicircuit Inc.	Minsu Lee, Korea Printed Circuit Association
	William H. Graver, NTS - Baltimore	David Lee, BMK Professional Electronics Gmb
	Chad Gustafson, TTM Technologies	Peggy LeGrand, TTM Technologies
	Vicka Hammill, Honeywell Inc. Air Transport Systems	Jeff Lewis, Holaday Circuits Inc.

Peter B. Lindhardt TTM Technologies - Logan Division	Jamie Noland, Blackfox Training Institute	Steven D. Roy, Roy Design and Manufacturing Service
Jennifer Ly, BAE Systems	Gerard A. O'Brien, Solderability Testing & Solutions, Inc.	Karl A. Sauter, Oracle America, Inc.
Clifford R. Maddox, Boeing Company	William A. Ortloff, Raytheon Company	Joseph C. Schmidt, Raytheon Missile Systems
Chris Mahanna, Robisan Laboratory Inc.	Gianluca Parodi, IIS Progress SRL	Mark William Scrimes, Raytheon Company
Jefferson Mao, Schweizer Electronic (Jiangsu) Co.,Ltd.	Gerry Partida, Summit Interconnect - Anaheim	Gilbert Shelby, Raytheon Systems Company
John B. Marke, UL LLC	Helena Pasquito, EPTAC Corporation	Russell S. Shepherd, NTS - Anaheim
Rene R. Martinez, Northrop Grumman Aerospace Systems	Yogen M. Patel, Candor Industries Inc.	Hans L. Shin, Pacific Testing Laboratories, Inc.
Daniel McCormick, NSWC Crane	Trevor Patterson, Hughes Circuits, Inc.	Patrick Smith, Cirexx International, Inc.
Tim McKliget, Holaday Circuits Inc.	Stephen Pierce, SGP Ventures, Inc.	David Sommervold, Henkel US Operations Corp.
Matthew T. McQueen, NSWC Crane	John A. Potenza, Lockheed Martin Mission Systems & Training	Bhanu Sood, NASA Goddard Space Flight Center
Melissa Meagher, Raytheon Missile Systems	Alan Preston, TTM Technologies	Brian Stevens, Collins Aerospace
Peter B. Menuez, L3Harris Technologies, Inc.	Owen Reid, Lockheed Martin Missiles & Fire Control	Marshall Hamilton Stolstrom, TTM Technologies, Inc.
Michael P. Miller, NSWC Crane	Yaoru Ren, Shengyi Electronics Co. Ltd.	Bradley E. Toone, L3Harris Communications
Timothy Minko, BAE Systems	Curtis R. Ricotta, Lockheed Martin Space Systems Company	Crystal E. Vanderpan, UL LLC
James J. Monarchio, TTM Technologies	Jose A. Rios, Raytheon	Jennet Volden, Collins Aerospace
Steven Murray, Northrop Grumman Corporation	Nef Rios, Summit Interconnect - Anaheim	Debbie Wade, Advanced Rework Technology-A.R.T
Thi V. Nguyen, Lockheed Martin Missile & Fire Control	Thomas Romont, IFTEC	

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